

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHEN FENG	05/23/2011
YU-QUAN WANG	05/23/2011
LIANG LIU	05/23/2011
LI QIAN	05/23/2011
RECEIVING PARTY DATA	
Name:	Beijing FUNATE Innovation Technology Co., LTD.
Street Address:	B1115, RD Plaza, Tsinghua Science Park, Shuangqing Road, Haidian District
City:	Beijing
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13114953
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Total Attachments: 2 source=US34821110521ASM#page1.tif source=US34821110521ASM#page2.tif	

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PATENT
 REEL: 026335 FRAME: 0775

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. CHEN FENG, residing at Beijing, China
2. YU-QUAN WANG, residing at Beijing, China
3. LIANG LIU, residing at Beijing, China
4. LI QIAN, residing at Beijing, China
5. _____, residing at _____
6. _____, residing at _____
7. _____, residing at _____
8. _____, residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **BEIJING FUNATE INNOVATION TECHNOLOGY CO., LTD.** having a principal place of business at **B1115, R&D Plaza, Tsinghua Science Park, Shuangqing Road, Haidian District, Beijing, P.R.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **CARBON NANOTUBE FILM SUPPORTING STRUCTURE AND METHOD FOR USING SAME** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____

[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Chen Feng</u> CHEN FENG	<u>May 23, 2011</u> Date
2.	<u>Yu-Quan Wang</u> YU-QUAN WANG	<u>May 23, 2011</u> Date
3.	<u>Ling Li</u> LIANG LIU	<u>May 23, 2011</u> Date
4.	<u>Li Qian</u> LI QIAN	<u>May 23, 2011</u> Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date